



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|---|
| Chip Size | 0603 |
| L | 1.6mm +0.2/-0.15mm (0.063 in +0.008/-0.006 in) |
| W | 0.81mm +0.2/-0.15mm (0.032 in +0.008/-0.006 in) |
| T | 1.02mm MAX (0.04 in MAX) |
| B | 0.41mm +/-0.2mm (0.016 in +/-0.008 in) |

Packaging Specifications

| | |
|--------------------|--------|
| Packaging | Waffle |
| Packaging Quantity | 368 |

General Information

| | |
|----------------|--|
| Series | SMD MIL BP PRF32535 |
| Style | SMD Chip |
| Description | SMD, Low ESR, MIL-PRF-32535 |
| RoHS | No |
| Prop 65 | ⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov |
| Termination | Solder Plated |
| Failure Rate | N/A |
| Qualifications | MIL-PRF-32535 M-Level |
| AEC-Q200 | No |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|---------------------------------|---------------------|
| Capacitance | 100 pF |
| Capacitance Tolerance | 10% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | BP |
| Dissipation Factor | 0.15% 1 MHz 25C |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)